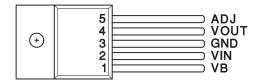
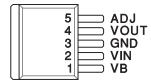
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- Fast Transient Response
- 10-mA to 5-A Load Current
- Short Circuit Protection
- Maximum Dropout of 500-mV at 5-A Load Current
- Separate Bias (VB) and VIN Pins
- Available in Adjustable or Fixed Output Voltages
- 5-Pin Package Allows Kelvin Sensing of Load Voltage
- Reverse Current Protection

### 5-PIN TO-220 T PACKAGE (TOP VIEW)



5-PIN TO-263 TD PACKAGE (TOP VIEW)



Note: Tab = Ground

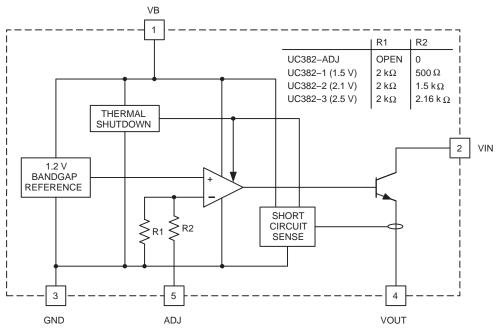
### description

The UC385 is a low dropout linear regulator providing a quick response to fast load changes. Combined with its precision onboard reference, the UC385 excels at driving GTL and BTL buses. Due to its fast response to load transients, the total capacitance required to decouple the regulator's output can be significantly decreased when compared to standard LDO linear regulators.

Dropout voltage (VIN to VOUT) is only 490 mV maximum and 350 mV typical at 5-A load (0°C to 100°C).

The onboard bandgap reference is stable with temperature and scaled for a 1.2 V input to the internal power amplifier. The UC385 is available in fixed output voltages of 1.5 V, 2.1 V, or 2.5 V. The output voltage of the adjustable version can be set with two external resistors. If the external resistors are omitted, the output voltage defaults to 1.2 V.

### block diagram





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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# UC285-1, UC285-2, UC285-3, UC285-ADJ, UC385-1, UC385-2, UC385-3, UC385-ADJ **FAST TRANSIENT RESPONSE 5-A** LOW-DROPOUT REGULATOR

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# absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

VIN	7.5 V
Output voltage	. 1.2 V to -6.0 V
Storage temperature	-65°C to 150°C
Junction temperature	-55°C to 150°C
Lead temperature (soldering, 10 seconds)	300°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### AVAILABLE OPTIONS(1)

	PACKAGED DEVICES											
_		TO-2	20 (T)		TO-263 (TD) <sup>(2)</sup>							
TJ		OUTPUT	VOLTAGE		OUTPUT VOLTAGE							
	1.5 V	2.1 V	2.5 V	1.2 V or ADJ	1.5 V	2.1 V	2.5 V	1.2 V or ADJ				
-40°C to 100°C	285T-1	285T-2	285T-3	285T-ADJ	285TD-1	285TD-2	285TD-3	285TD-ADJ				
0°C to 100°C	385T-1	385T-2	385T-3	385T-ADJ	385TD-1	385TD-2	385TD-3	385TD-ADJ				

- 1. For more package and ordering information, see the Package Option Addendum located at the end of this data sheet.
- 2. For 50 piece reel, add KTTT (e.g., UC285TDKTTT-1); for 500 piece reel, add TR (e.g., UC285TDTR-1).

### electrical characteristics unless otherwise stated, these parameters apply for $T_A = -40^{\circ}$ C to $100^{\circ}$ C for the UC285-x series and 0°C to 100°C for the UC385-x, VB = 5 V; VIN = 3.3 V, VOUT = 2.5 V, $T_A = T_J$ .

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
UC385-3 Fixed 2.5 V, 5-A Family			•			
Output voltage	UC385-3	I <sub>VOUT</sub> = 100 mA	2.475	2.5	2.525	V
	UC285-3	I <sub>VOUT</sub> = 100 mA	2.45	2.5	2.525	V
Load regulation		I <sub>VOUT</sub> = 10 mA to 5 A		0.5	4	mV
VIN PSRR			80	110		dB
VB PSRR			50	65		dB
VIN dropout voltage (VIN - VOUT)		I <sub>VOUT</sub> = 5 A, T <sub>J</sub> = 25°C		350	425	mV
	UC385-3	I <sub>VOUT</sub> = 5 A		350	490	mV
	UC285-3	I <sub>VOUT</sub> = 5 A		350	500	mV
VB dropout (VB - VOUT)	UC385-3	I <sub>VOUT</sub> = 5 A		1.8	2.1	V
	UC285-3	I <sub>VOUT</sub> = 5 A		1.8	2.2	V
Short circuit current limit			5.1		7.5	Α
VB current		I <sub>VOUT</sub> = 10 mA		8	15	mA
		I <sub>VOUT</sub> = 5 A		40	100	mA
VIN current		I <sub>VOUT</sub> = 5 A	4.9	4.96		Α
UC385-2 Fixed 2.1 V, 5-A Family						
Output voltage	UC385-2	I <sub>VOUT</sub> = 100 mA	2.079	2.1	2.121	V
	UC285-2	I <sub>VOUT</sub> = 100 mA	2.058	2.1	2.121	V
Load regulation		I <sub>VOUT</sub> = 10 mA to 5 A		0.5	4	mV
VIN PSRR			80	110		dB
VB PSRR			50	67		dB



# UC285-1, UC285-2, UC285-3, UC285-ADJ, UC385-1, UC385-2, UC385-3, UC385-ADJ FAST TRANSIENT RESPONSE 5-A LOW-DROPOUT REGULATOR

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# electrical characteristics unless otherwise stated, these parameters apply for $T_A = -40^{\circ}C$ to $100^{\circ}C$ for the UC285-x series and $0^{\circ}C$ to $100^{\circ}C$ for the UC385-x, VB = 5 V; VIN = 3.3 V, VOUT = 2.5 V, $T_A = T_J$ .

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
UC385-2 Fixed 2.1 V, 5-A Family (con	tinued)					ı
VIN dropout voltage (VIN - VOUT)		I <sub>VOUT</sub> = 5 A, T <sub>J</sub> = 25°C		350	425	mV
	UC385-2	IVOUT = 5 A		350	490	mV
	UC285-2	I <sub>VOUT</sub> = 5 A		350	500	mV
VB dropout (VB - VOUT)	UC385-2	I <sub>VOUT</sub> = 5 A		1.8	2.1	V
	UC285-2	IVOUT = 5 A		1.8	2.2	V
Short circuit current limit	•		5.1		7.5	Α
VB current		I <sub>VOUT</sub> = 10 mA		8	15	mA
		IVOUT = 5 A		40	100	mA
VIN current		I <sub>VOUT</sub> = 5 A	4.9	4.96		Α
UC385-1 Fixed 1.5 V, 5-A Family			<b>'</b>			ı
Output voltage	UC385-1	I <sub>VOUT</sub> = 100 mA	1.485	1.5	1.515	V
	UC285-1	I <sub>VOUT</sub> = 100 mA	1.470	1.5	1.515	V
Load regulation	•	IVOUT = 10 mA to 5 A		0.5	4	mV
VIN PSRR			80	110		dB
VB PSRR			50	65		dB
VIN dropout voltage (VIN - VOUT)		I <sub>VOUT</sub> = 5 A, T <sub>J</sub> = 25°C		350	425	mV
	UC285-1	I <sub>VOUT</sub> 5 A		350	490	mV
	UC285-2	I <sub>VOUT</sub> = 5 A		350	500	mV
VB dropout (VB - VOUT)	UC385-1	I <sub>VOUT</sub> = 5 A		1.8	2.1	V
	UC285-1	I <sub>VOUT</sub> = 5 A		1.8	2.2	V
Short circuit current limit	<u>.</u>		5.1		7.5	Α
VB current		I <sub>VOUT</sub> = 10 mA		8	15	mA
		I <sub>VOUT</sub> = 5 A		40	100	mA
VIN = current		I <sub>VOUT</sub> = 5 A	4.9	4.96		Α
UC385-ADJ Adjustable, 5-A Family			<b>.</b>			
ADJ voltage	UC385-ADJ	I <sub>VOUT</sub> - 100 mA	1.188	1.2	1.212	V
	UC285-ADJ	I <sub>VOUT</sub> - 100 mA	1.176	1.2	1.212	V
Load regulation	•	I <sub>VOUT</sub> = 10 mA to 5 A		0.5	4	mV
VIN PSRR		VOUT programmed for 2.5 V	80	110		dB
VB PSRR VOUT		Programmed for 2.5 V	50	65		dB
VIN dropout voltage (VIN - VOUT)		I <sub>VOUT</sub> = 5 A, T <sub>J</sub> = 25°C		350	425	mV
	UC385-ADJ	I <sub>VOUT</sub> = 5 A		350	490	mV
	UC285-ADJ	I <sub>VOUT</sub> = 5 A		350	500	mV
VB dropout (VB - VOUT) UC38		I <sub>VOUT</sub> = 5 A		1.8	2.1	V
	UC285-ADJ	I <sub>VOUT</sub> = 5 A		1.8	2.2	V
Short circuit current limit			5.1		7.5	Α
VB current		I <sub>VOUT</sub> = 10 mA		8	15	mA
		I <sub>VOUT</sub> = 5 A		40	100	mA
VIN current		I <sub>VOUT</sub> = 5 A	4.9	4.96		Α



## UC285-1, UC285-2, UC285-3, UC285-ADJ, UC385-1, UC385-2, UC385-3, UC385-ADJ FAST TRANSIENT RESPONSE 5-A LOW-DROPOUT REGULATOR

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### pin descriptions

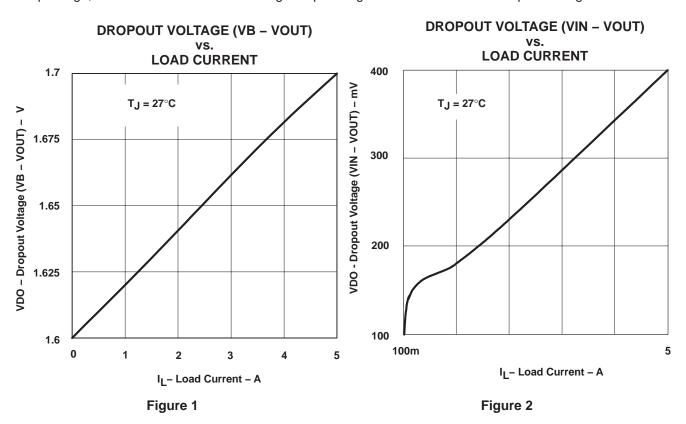
**ADJ:** In the adjustable version, the user programs the output voltage with two external resistors. The resistors should be 0.1% for high accuracy. The output amplifier is configured as a noninverting operational amplifier. The resistors should meet the criteria of R3 || R4 < 100  $\Omega$ . Connect ADJ to VOUT for an output voltage of 1.2 V. Note that the point at which the feedback network is connected to the output is the Kelvin sense point.

GND: For accurate results, the GND pin should be referenced to the load ground.

VB: Supplies power to all circuits of the regulator except the output power transistor. The 2-V headroom from VB to VOUT allows the use of a Darlington output stage for inherently low output impedance and fast response. (Dropout is derated for junction temperatures below 0°C.)

VIN: Supplies the current to the collector of the output power transistor only. The dropout (VIN-VOUT) is under 100 mV for light loads; maximum dropout is 490 mV at 5 A for T<sub>.1</sub> = 0°C to 100°C. (Dropout is derated for junction temperatures over 100°C.)

VOUT: This pin should be connected to the load via a low impedance path. Avoid connectors which add significant inductance and resistance. Note that even though a Kelvin sense is available through a 5-pin package, care must be taken since voltage drops along wire traces add to the dropout voltage.



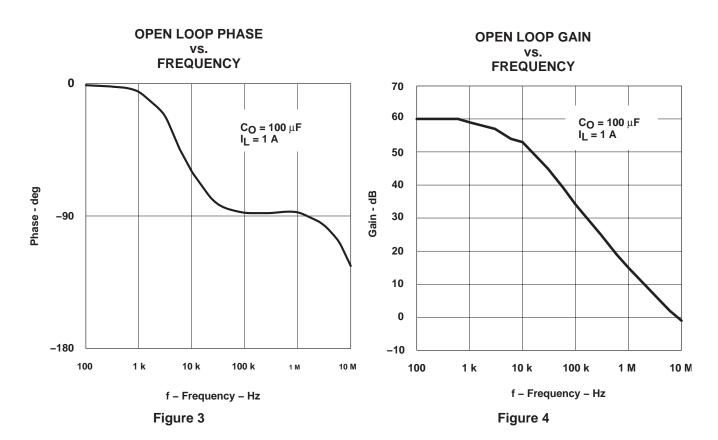
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### **APPLICATION INFORMATION**

The UC385 is easy to use. The adjustable version requires two resistors to set the output voltage. The fixed versions of the UC385 require no external resistors. All versions of the UC385 require decoupling capacitors on the input and output. In a typical application, VB and VIN are driven from switching power supplies which may have large filter capacitors at their outputs. If the UC385 is further than 12 inches from the power supply, it is recommended to add local decoupling as close as possible to the linear regulator.

Decouple the output of the UC385 with at least 100  $\mu$ F of high quality tantalum or Sanyo OSCON capacitors close to the VOUT pin for maximum stability. Many applications involving ultrafast GTL or BTL applications require additional capacitance close to the load. The exact amount will vary according to speed and magnitude of the load transients and the tolerance allowed for transients on VOUT. When specifying the decoupling capacitors, the series resistance of the capacitor bank is an important factor in its ability to filter load transients.

The UC385 allows for Kelvin sensing the voltage at the load. This improves regulation performance and eliminates the voltage drops due to wire trace resistance. This voltage drop must be added to the headroom (VIN to VOUT and VB to VOUT). The dropout of 350 mV is measured at the pins and does not include additional drops due to trace resistance.



### **APPLICATION INFORMATION**

### POWER SUPPLY REJECTION RATIO (VB INPUT)

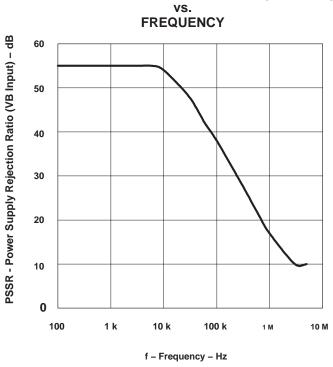
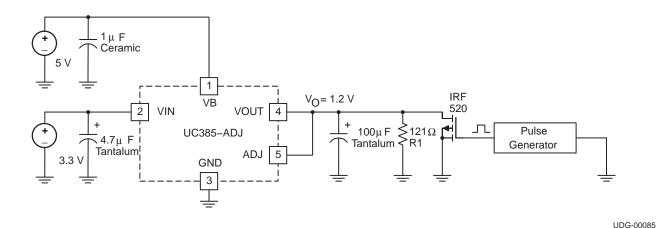


Figure 5



**Figure 6. Transient Test Circuit** 



### **APPLICATION INFORMATION**

### 10 mA to 3 A/μs Load Transient Response

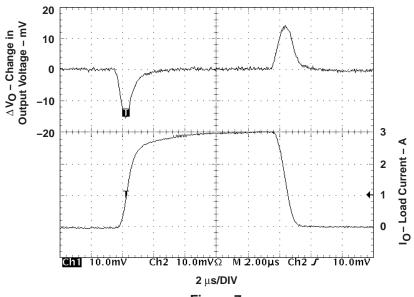
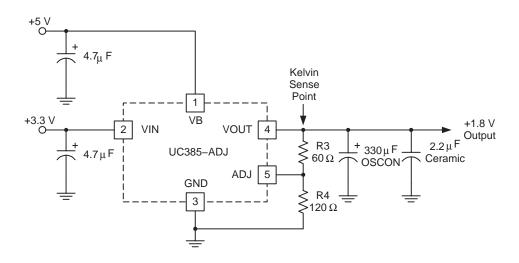


Figure 7



UDG-00086

Figure 8. Typical UC385-ADJ Application

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### **APPLICATION INFORMATION**

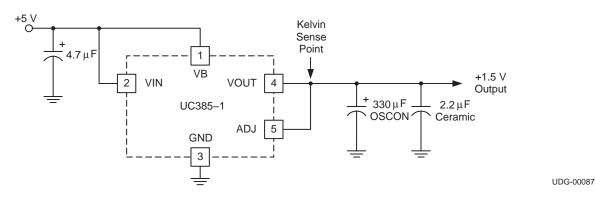


Figure 9. Typical UC385-1, -2, or -3 Application





### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UC285T-1	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC285T-1G3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC285T-3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC285T-3G3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC285T-ADJ	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC285T-ADJG3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC285TD-1	OBSOLETE	DDPAK/ TO-263	KTT	5		TBD	Call TI	Call TI
UC285TD-2	OBSOLETE	DDPAK/ TO-263	KTT	5		TBD	Call TI	Call TI
UC285TD-3	OBSOLETE	DDPAK/ TO-263	KTT	5		TBD	Call TI	Call TI
UC285TD-ADJ	OBSOLETE	DDPAK/ TO-263	KTT	5		TBD	Call TI	Call TI
UC285TDKTTT-1	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC285TDKTTT-1G3	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC285TDKTTT-3	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC285TDKTTT-3G3	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC285TDKTTT-ADJ	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC285TDKTTT-ADJG3	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385T-1	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC385T-1G3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC385T-2	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC385T-2G3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC385T-3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC385T-3G3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC385T-ADJ	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC385T-ADJG3	ACTIVE	TO-220	KC	5	50	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type
UC385TD-1	OBSOLETE	DDPAK/ TO-263	KTT	5		TBD	Call TI	Call TI





18-Sep-2008

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UC385TD-2	OBSOLETE	DDPAK/ TO-263	KTT	5		TBD	Call TI	Call TI
UC385TD-3	OBSOLETE	DDPAK/ TO-263	KTT	5		TBD	Call TI	Call TI
UC385TD-ADJ	OBSOLETE	DDPAK/ TO-263	KTT	5		TBD	Call TI	Call TI
UC385TDKTTT-1	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDKTTT-1G3	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDKTTT-3	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDKTTT-3G3	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDKTTT-ADJ	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDKTTT-ADJG3	ACTIVE	DDPAK/ TO-263	KTT	5	50	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDTR-1	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDTR-1G3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDTR-3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDTR-3G3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDTR-ADJ	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDTR-ADJE3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TDTR-ADJG3	ACTIVE	DDPAK/ TO-263	KTT	5	500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR
UC385TH-ADJ	OBSOLETE	TO-220	KC	5		TBD	Call TI	Call TI

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): Tl's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



### PACKAGE OPTION ADDENDUM

18-Sep-2008

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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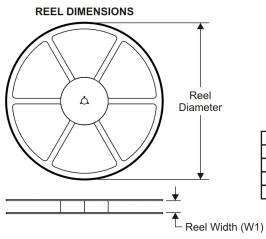
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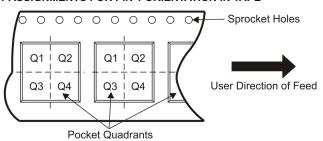
### TAPE AND REEL INFORMATION



# TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC285TDKTTT-1	DDPAK/ TO-263	KTT	5	50	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2
UC285TDKTTT-3	DDPAK/ TO-263	KTT	5	50	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2
UC285TDKTTT-ADJ	DDPAK/ TO-263	KTT	5	50	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2
UC385TDKTTT-1	DDPAK/ TO-263	KTT	5	50	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2
UC385TDKTTT-3	DDPAK/ TO-263	KTT	5	50	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2
UC385TDKTTT-ADJ	DDPAK/ TO-263	KTT	5	50	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2
UC385TDTR-1	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2
UC385TDTR-3	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2
UC385TDTR-ADJ	DDPAK/ TO-263	KTT	5	500	330.0	24.4	10.6	15.6	4.9	16.0	24.0	Q2



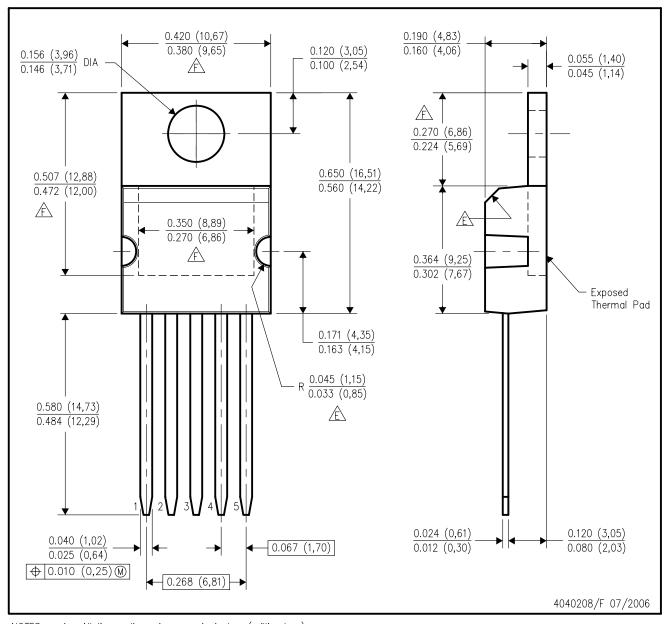


\*All dimensions are nominal

		1					
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC285TDKTTT-1	DDPAK/TO-263	KTT	5	50	346.0	346.0	41.0
UC285TDKTTT-3	DDPAK/TO-263	KTT	5	50	346.0	346.0	41.0
UC285TDKTTT-ADJ	DDPAK/TO-263	KTT	5	50	346.0	346.0	41.0
UC385TDKTTT-1	DDPAK/TO-263	KTT	5	50	346.0	346.0	41.0
UC385TDKTTT-3	DDPAK/TO-263	KTT	5	50	346.0	346.0	41.0
UC385TDKTTT-ADJ	DDPAK/TO-263	KTT	5	50	346.0	346.0	41.0
UC385TDTR-1	DDPAK/TO-263	KTT	5	500	346.0	346.0	41.0
UC385TDTR-3	DDPAK/TO-263	KTT	5	500	346.0	346.0	41.0
UC385TDTR-ADJ	DDPAK/TO-263	KTT	5	500	346.0	346.0	41.0

# KC (R-PSFM-T5)

# PLASTIC FLANGE-MOUNT PACKAGE



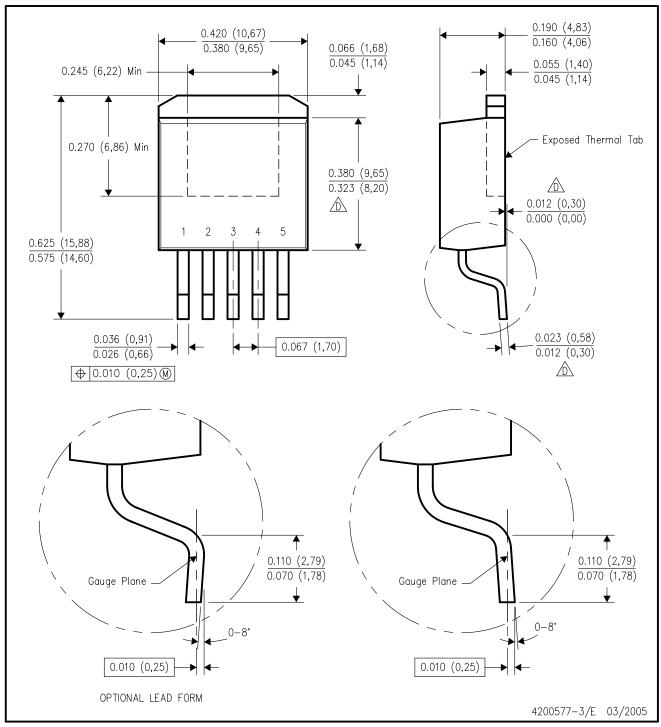
NOTES: A.

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. All lead dimensions apply before solder dip.
- D. The center lead is in electrical contact with the mounting tab.
- These features are optional.
- Thermal pad contour optional within these dimensions.



# KTT (R-PSFM-G5)

# PLASTIC FLANGE-MOUNT PACKAGE

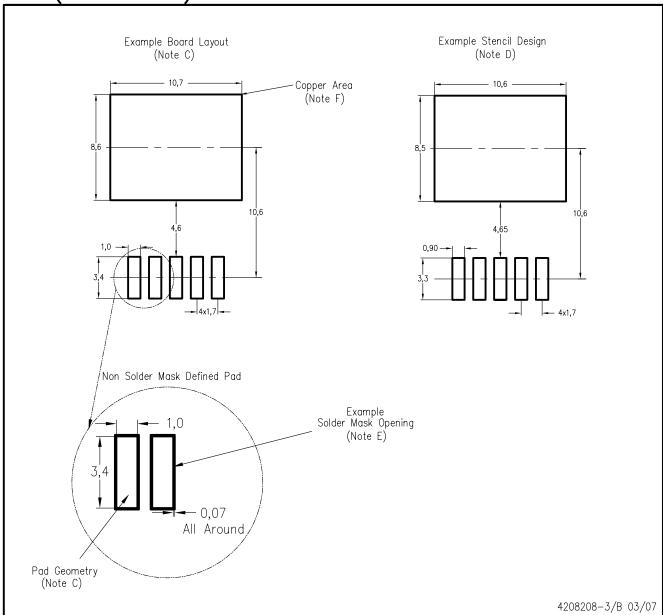


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
- Falls within JEDEC TO-263 variation BA, except minimum lead thickness, maximum seating height, and minimum body length.



KTT (R-PSFM-G5)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release.

  Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
- F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.



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